

ABSTRACT

A surface acoustic wave filter which can prevent the formation of large voids when pressing a resin sheet covering a device chip while heating the resin sheet, and a method of producing the same are provided.

In a device chip 10, a principal surface 11a of a piezoelectric substrate 11 having a wiring pattern including IDTs 14 and pads 16 electrically connected to the IDTs 14 is disposed so as to oppose a mount board 2, with the pads 16 being electrically connected to lands 3 of the mount board 2 through bumps 4. A resin film 6 covers the other principal surface 11b of the piezoelectric substrate 11 and the other principal surface of the mount board 2 to seal the device chip 10. In the piezoelectric substrate 11, the principal surface 11a is relatively large and the other principal surface 11b is relatively small.